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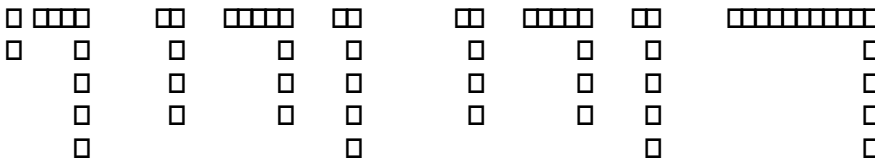
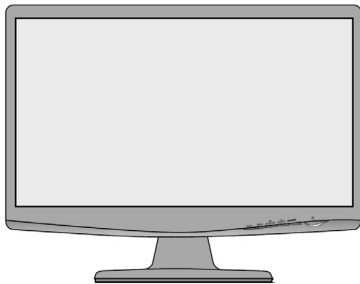
COLOR MONITOR

SERVICE MANUAL

MODEL **FLATRON W2243S** (W2243S-PFT.A**NAVH for
LGD TLA1, W2243S-PFT.A**VAVH for AUO V0) **Sales Market

CAUTION

BEFORE SERVICING THE UNIT,
READ THE **SAFETY PRECAUTIONS** IN THIS MANUAL.



To Apply the Novatek Chip

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SPECIFICATIONS

1. LCD CHARACTERISTICS

Type: matrix-TFT Color LCD Module

Active Display Area: 21.53 inches

Pixel Pitch: 0.248 (H) x 0.248 (V)mm

Color Depth: 16.7M colors

Size: 495.6(W) x 292.2(H) x 16.35(D) mm(Typ.)

Display Mode: LTN Mode, Normally White

Surface Treatment: Anti-Glare, 3H

Electrical Interface: Dual channel LVDS

2. OPTICAL CHARACTERISTICS

2-1. Viewing Angle by Contrast Ratio > 10

Left: 150°min, 170°(Typ) Right: 150°min, 170°(Typ)

Top: 140° min, 160°(Typ) Bottom: 140°min,160°(Typ)

2-2. White Luminance (Center): 300Cd / m² (Typ)

2-3. Contrast Ratio: 600(min), 1000(Typ)

3. SIGNAL (Refer to the Timing Chart)

3-1. Sync Signal

Type: Separate Sync, SOG (Sync On Green)

3-2. Video Input Signal

1) Type: R, G, B Analog

2) Voltage Level: 0~0.7 Vp-p

3) Input impedance: 75 Ω

3-3. Operating Frequency

Horizontal: 30 ~ 83kHz

Vertical: 56 ~ 75Hz

4. Max. Resolution

D-sub Analog: VESA 1920 x 1080 @ 60 Hz

5. POWER SUPPLY

5-1. Power: AC 100-240V~ 50/60Hz 1.0A

5-2. Power Consumption

On Mode: 40 W(Typ.)

Sleep Mode: ≤ 1 W

Off Mode: ≤ 1 W

6. ENVIRONMENT

6-1. Operating

Temperature: 10°C~35°C

Humidity: 10 % to 80 % non-Condensing

6-2. Storage

Temperature: -20°C to 60 °C

Humidity: 5 % to 90 % non-Condensing

6-3. MTBF: ≥70000 Hours (Not include panel)

Lamp Life: ≥50000 Khrs

7. DIMENSIONS (with Stand)

Width: 51.64 cm (20.33 inches)

Depth: 19.80 cm (7.80 inches)

Height: 39.61 cm (15.59 inches)

8. WEIGHT (excl. packing)

Weight: 3.8 kg (8.38 lbs)

PRECAUTION

WARNING FOR THE SAFETY-RELATED COMPONENT.

- There are some special components used in LCD monitor that are important for safety. **These parts are marked ⚠ on the schematic diagram and the Exploded View.** It is essential that these critical parts should be replaced with the manufacturer's specified parts to prevent electric shock, fire or other hazard.
- Do not modify original design without obtaining written permission from manufacturer or you will void the original parts and labor guarantee.

TAKE CARE DURING HANDLING THE LCD MODULE WITH BACKLIGHT UNIT.

- Must mount the module using mounting holes arranged in four corners.
- Do not press on the panel, edge of the frame strongly or electric shock as this will result in damage to the screen.
- Do not scratch or press on the panel with any sharp objects, such as pencil or pen as this may result in damage to the panel.
- Protect the module from the ESD as it may damage the electronic circuit (C-MOS).
- Make certain that treatment person's body are grounded through wrist band.
- Do not leave the module in high temperature and in areas of high humidity for a long time.
- The module not be exposed to the direct sunlight.
- Avoid contact with water as it may a short circuit within the module.
- If the surface of panel become dirty, please wipe it off with a soft material. (Cleaning with a dirty or rough cloth may damage the panel.)

⚠ CAUTION

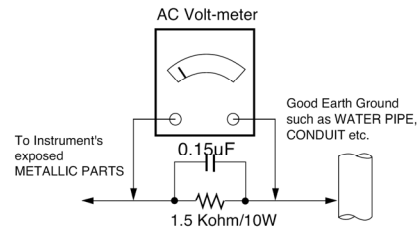
Please use only a plastic screwdriver to protect yourself from shock hazard during service operation.

⚠ WARNING

BE CAREFUL ELECTRIC SHOCK !

- If you want to replace with the new backlight (CCFL) or LIPS part, must disconnect the AC power because high voltage appears at inverter circuit about 650Vrms.
- Handle with care wires or connectors of the inverter circuit. If the wires are pressed cause short and may burn or take fire.

Leakage Current Hot Check Circuit



When 25A is impressed between Earth and 2nd Ground for 1 second, Resistance must be less than 0.1 Ω
*Base on Adjustment standard

• Replaceable batteries

* CAUTION

RISK OF EXPLOSION IF BATTERY IS REPLACED BY AN INCORRECT TYPE.
DISPOSE OF USED BATTERIES ACCORDING TO THE INSTRUCTIONS

SERVICING PRECAUTIONS

CAUTION: Before servicing receivers covered by this service manual and its supplements and addenda, read and follow the **SAFETY PRECAUTIONS** on page 3 of this publication.

NOTE: If unforeseen circumstances create conflict between the following servicing precautions and any of the safety precautions on page 3 of this publication, always follow the safety precautions. Remember: Safety First.

General Servicing Precautions

1. Always unplug the receiver AC power cord from the AC power source before;
 - a. Removing or reinstalling any component, circuit board module or any other receiver assembly.
 - b. Disconnecting or reconnecting any receiver electrical plug or other electrical connection.
 - c. Connecting a test substitute in parallel with an electrolytic capacitor in the receiver.
CAUTION: A wrong part substitution or incorrect polarity installation of electrolytic capacitors may result in an explosion hazard.
 - d. Discharging the picture tube anode.
2. Test high voltage only by measuring it with an appropriate high voltage meter or other voltage measuring device (DVM, FETVOM, etc) equipped with a suitable high voltage probe.
Do not test high voltage by "drawing an arc".
3. Discharge the picture tube anode only by (a) first connecting one end of an insulated clip lead to the degaussing or kine aquadag grounding system shield at the point where the picture tube socket ground lead is connected, and then (b) touch the other end of the insulated clip lead to the picture tube anode button, using an insulating handle to avoid personal contact with high voltage.
4. Do not spray chemicals on or near this receiver or any of its assemblies.
5. Unless specified otherwise in this service manual, clean electrical contacts only by applying the following mixture to the contacts with a pipe cleaner, cotton-tipped stick or comparable non-abrasive applicator; 10% (by volume) Acetone and 90% (by volume) isopropyl alcohol (90%-99% strength)
CAUTION: This is a flammable mixture.
Unless specified otherwise in this service manual, lubrication of contacts is not required.
6. Do not defeat any plug/socket B+ voltage interlocks with which receivers covered by this service manual might be equipped.
7. Do not apply AC power to this instrument and/or any of its electrical assemblies unless all solid-state device heat sinks are correctly installed.
8. Always connect the test receiver ground lead to the receiver chassis ground before connecting the test receiver positive lead.
Always remove the test receiver ground lead last.

9. Use with this receiver only the test fixtures specified in this service manual.

CAUTION: Do not connect the test fixture ground strap to any heat sink in this receiver.

Electrostatically Sensitive (ES) Devices

Some semiconductor (solid-state) devices can be damaged easily by static electricity. Such components commonly are called *Electrostatically Sensitive (ES) Devices*. Examples of typical ES devices are integrated circuits and some field-effect transistors and semiconductor "chip" components. The following techniques should be used to help reduce the incidence of component damage caused by static by static electricity.

1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed to prevent potential shock reasons prior to applying power to the unit under test.
2. After removing an electrical assembly equipped with ES devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
3. Use only a grounded-tip soldering iron to solder or unsolder ES devices.
4. Use only an anti-static type solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ES devices.
5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ES devices.
6. Do not remove a replacement ES device from its protective package until immediately before you are ready to install it. (Most replacement ES devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive material).
7. Immediately before removing the protective material from the leads of a replacement ES device, touch the protective material to the chassis or circuit assembly into which the device will be installed.
CAUTION: Be sure no power is applied to the chassis or circuit, and observe all other safety precautions.
8. Minimize bodily motions when handling unpackaged replacement ES devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ES device.)

General Soldering Guidelines

1. Use a grounded-tip, low-wattage soldering iron and appropriate tip size and shape that will maintain tip temperature within the range of 500° F to 600° F.
2. Use an appropriate gauge of RMA resin-core solder composed of 60 parts tin/40 parts lead.
3. Keep the soldering iron tip clean and well tinned.
4. Thoroughly clean the surfaces to be soldered. Use a small wire-bristle (0.5 inch, or 1.25cm) brush with a metal handle.

Do not use freon-propelled spray-on cleaners.

5. Use the following unsoldering technique
 - a. Allow the soldering iron tip to reach normal temperature.
(500° F to 600° F)
 - b. Heat the component lead until the solder melts.
 - c. Quickly draw the melted solder with an anti-static, suction-type solder removal device or with solder braid.

CAUTION: Work quickly to avoid overheating the circuitboard printed foil.

6. Use the following soldering technique.
 - a. Allow the soldering iron tip to reach a normal temperature (500° F to 600° F)
 - b. First, hold the soldering iron tip and solder the strand against the component lead until the solder melts.
 - c. Quickly move the soldering iron tip to the junction of the component lead and the printed circuit foil, and hold it there only until the solder flows onto and around both the component lead and the foil.

CAUTION: Work quickly to avoid overheating the circuit board printed foil.

- d. Closely inspect the solder area and remove any excess or splashed solder with a small wire-bristle brush.

IC Remove/Replacement

Some chassis circuit boards have slotted holes (oblong) through which the IC leads are inserted and then bent flat against the circuit foil. When holes are the slotted type, the following technique should be used to remove and replace the IC. When working with boards using the familiar round hole, use the standard technique as outlined in paragraphs 5 and 6 above.

Removal

1. Desolder and straighten each IC lead in one operation by gently prying up on the lead with the soldering iron tip as the solder melts.
2. Draw away the melted solder with an anti-static suction-type solder removal device (or with solder braid) before removing the IC.

Replacement

1. Carefully insert the replacement IC in the circuit board.
2. Carefully bend each IC lead against the circuit foil pad and solder it.
3. Clean the soldered areas with a small wire-bristle brush. (It is not necessary to reapply acrylic coating to the areas).

"Small-Signal" Discrete Transistor

Removal/Replacement

1. Remove the defective transistor by clipping its leads as close as possible to the component body.
2. Bend into a "U" shape the end of each of three leads remaining on the circuit board.
3. Bend into a "U" shape the replacement transistor leads.
4. Connect the replacement transistor leads to the corresponding leads extending from the circuit board and crimp the "U" with long nose pliers to insure metal to metal contact then solder each connection.

Power Output, Transistor Device

Removal/Replacement

1. Heat and remove all solder from around the transistor leads.
2. Remove the heat sink mounting screw (if so equipped).
3. Carefully remove the transistor from the heat sink of the circuit board.
4. Insert new transistor in the circuit board.
5. Solder each transistor lead, and clip off excess lead.
6. Replace heat sink.

Diode Removal/Replacement

1. Remove defective diode by clipping its leads as close as possible to diode body.
2. Bend the two remaining leads perpendicular y to the circuit board.
3. Observing diode polarity, wrap each lead of the new diode around the corresponding lead on the circuit board.
4. Securely crimp each connection and solder it.
5. Inspect (on the circuit board copper side) the solder joints of the two "original" leads. If they are not shiny, reheat them and if necessary, apply additional solder.

Fuse and Conventional Resistor

Removal/Replacement

1. Clip each fuse or resistor lead at top of the circuit board hollow stake.
2. Securely crimp the leads of replacement component around notch at stake top.
3. Solder the connections.

CAUTION: Maintain original spacing between the replaced component and adjacent components and the circuit board to prevent excessive component temperatures.

Circuit Board Foil Repair

Excessive heat applied to the copper foil of any printed circuit board will weaken the adhesive that bonds the foil to the circuit board causing the foil to separate from or "lift-off" the board. The following guidelines and procedures should be followed whenever this condition is encountered.

At IC Connections

To repair a defective copper pattern at IC connections use the following procedure to install a jumper wire on the copper pattern side of the circuit board. (Use this technique only on IC connections).

1. Carefully remove the damaged copper pattern with a sharp knife. (Remove only as much copper as absolutely necessary).
2. Carefully scratch away the solder resist and acrylic coating (if used) from the end of the remaining copper pattern.
3. Bend a small "U" in one end of a small gauge jumper wire and carefully crimp it around the IC pin. Solder the IC connection.
4. Route the jumper wire along the path of the out-away copper pattern and let it overlap the previously scraped end of the good copper pattern. Solder the overlapped area and clip off any excess jumper wire.

At Other Connections

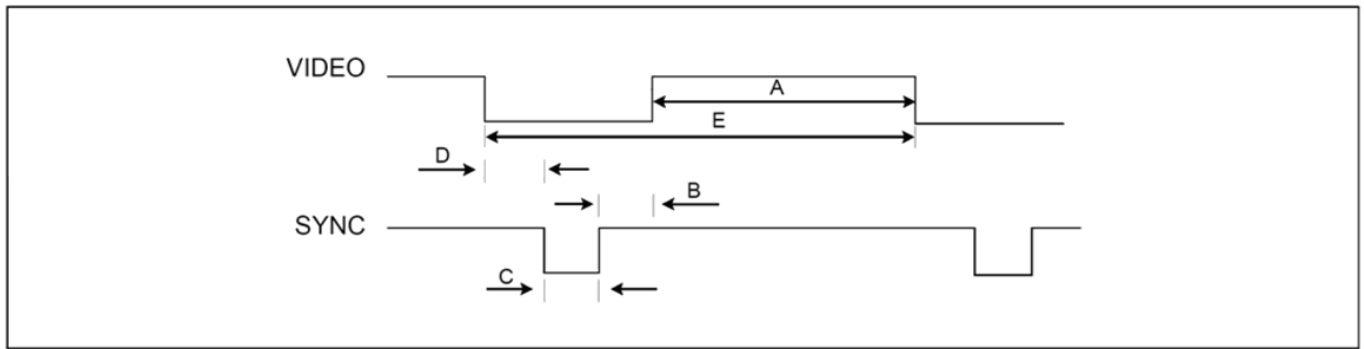
Use the following technique to repair the defective copper pattern at connections other than IC Pins. This technique involves the installation of a jumper wire on the component side of the circuit board.

1. Remove the defective copper pattern with a sharp knife.
Remove at least 1/4 inch of copper, to ensure that a hazardous condition will not exist if the jumper wire opens.
2. Trace along the copper pattern from both sides of the pattern break and locate the nearest component that is directly connected to the affected copper pattern.
3. Connect insulated 20-gauge jumper wire from the lead of the nearest component on one side of the pattern break to the lead of the nearest component on the other side.

Carefully crimp and solder the connections.

CAUTION: Be sure the insulated jumper wire is dressed so the it does not touch components or sharp edges.

TIMING CHART



Mode	Section	Polarity	DOT CLOCK [MHz]	Frequency [kHz]/[Hz]	Total Period(E)	Display (A)	Front Porch (D)	Syn c. (C)	Back Porch (B)	Resol- ution
1	H(Pixels)	+	25.175	31.469	800	640	16	96	48	640 x
	V(Lines)	-		70.09	449	350	37	2	60	350
2	H(Pixels)	-	28.321	31.468	900	720	18	108	54	720 X
	V(Lines)	+		70.08	449	400	12	2	35	400
3	H(Pixels)	-	25.175	31.469	800	640	16	96	48	640 x
	V(Lines)	-		59.94	525	480	10	2	33	480
4	H(Pixels)	-	31.5	37.5	840	640	16	64	120	640 x
	V(Lines)	-		75	500	480	1	3	16	480
5	H(Pixels)	+	40.0	37.879	1056	800	40	128	88	800 x
	V(Lines)	+		60.317	628	600	1	4	23	600
6	H(Pixels)	+	49.5	46.875	1056	800	16	80	160	800 x
	V(Lines)	+		75.0	625	600	1	3	21	600
7	H(Pixels)	+/-	57.283	49.725	1152	832	32	64	224	832 x
	V(Lines)	+/-		74.55	667	624	1	3	39	624
8	H(Pixels)	-	65.0	48.363	1344	1024	24	136	160	1024 x
	V(Lines)	-		60.0	806	768	3	6	29	768

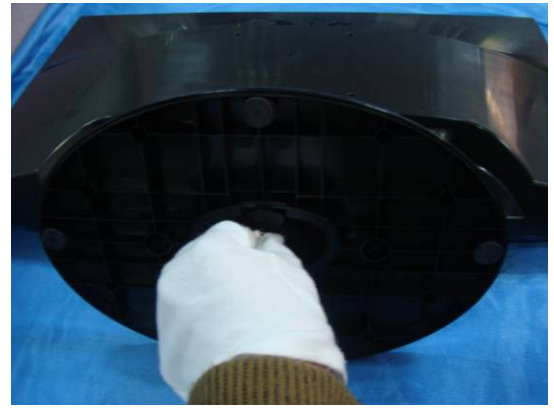
Mode	Section	Polarity	DOT CLOCK [MHz]	Frequency [kHz]/[Hz]	Total Period(E)	Display (A)	Front Porch (D)	Sync . (C)	Back Porch (B)	Resol- ution
9	H(Pixels)	-	78.75	60.123	1312	1024	16	96	176	1024 x
	V(Lines)	-		75.029	800	768	1	3	28	768
10	H(Pixels)	+/-	100.0	68.681	1456	1152	32	128	144	1152 x
	V(Lines)	+/-		75.062	915	870	3	3	39	870
11	H(Pixels)	+/-	92.978	61.805	1504	1152	18	134	200	1152 x
	V(Lines)	+/-		65.96	937	900	2	4	31	900
12	H(Pixels)	+	108.0	63.981	1688	1280	48	112	248	1280 x
	V(Lines)	+		60.02	1066	1024	1	3	38	1024
13	H(Pixels)	+	135.0	79.976	1688	1280	16	144	248	1280 x
	V(Lines)	+		75.035	1066	1024	1	3	38	1024
14	H(Pixels)	+	119.00	64.674	1840	1680	48	32	80	1680 x
	V(Lines)	-		59.883	1080	1050	3	6	21	1050
15	H(Pixels)	-	146.250	65.290	2240	1680	104	176	280	1680 x
	V(Lines)	+		59.954	1089	1050	3	6	30	1050
16	H(Pixels)	+	105.982	63.981	1688	1280	48	112	248	1280 x
	V(Lines)	+		60.02	1062	1024	1	3	34	1024
17	H(Pixels)	+	148.50	67.5	2200	1920	88	44	143	1920 x
	V(Lines)	+		60	1125	1080	4	5	36	1080

DISASSEMBLY-Set

#1

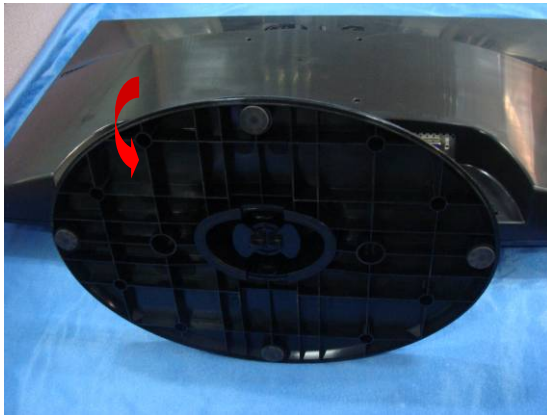


#2



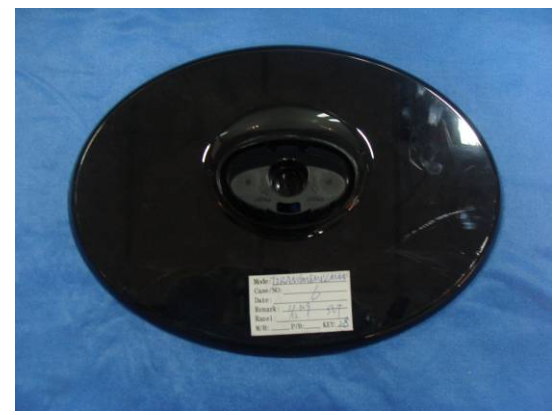
Put the monitor on a soft flat.

#3



Revolve the release button.

#4



Consequently, pull the base directly.

#5



Put the front cover upward. Then let the all latches are separated.

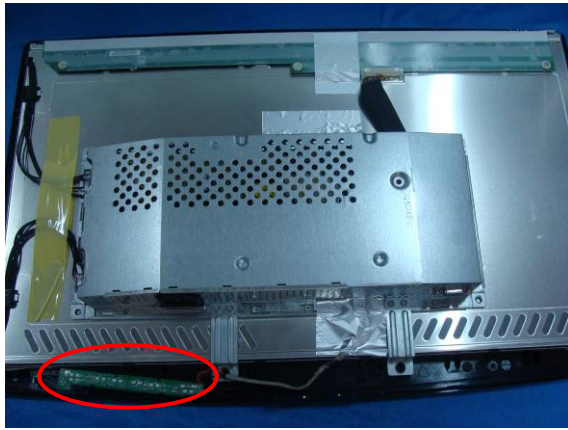
The base.

#6



Put the front face down, disassembly back cover.

#7



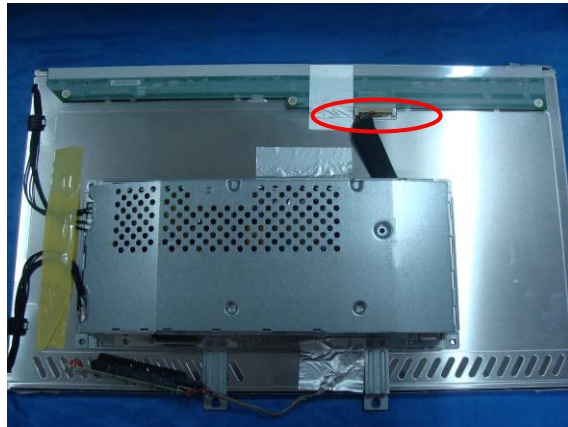
Pull the key board out of bezel.

#8



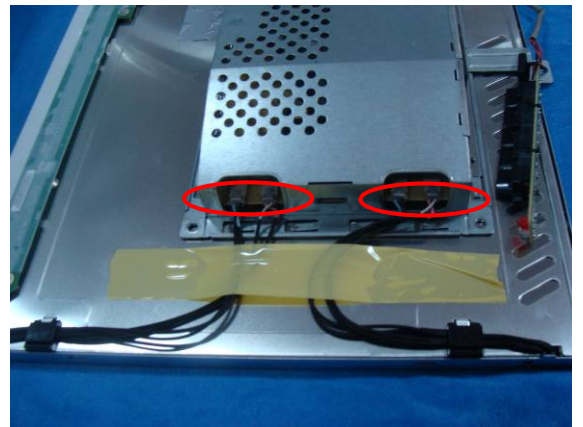
Disassembly the bezel.

#9



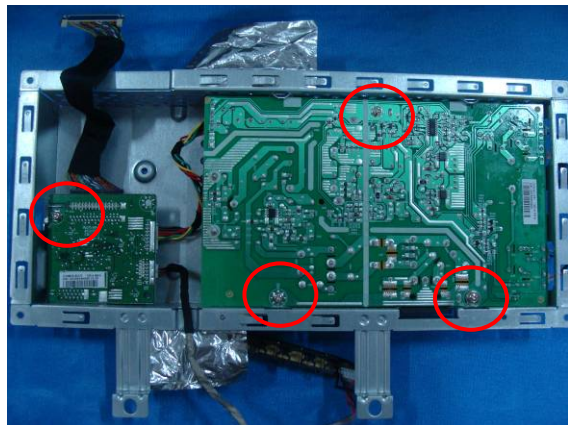
Disassembly the LVDS cable.

#10



Disassemble the connector.

#11



Main board and power board.

#12



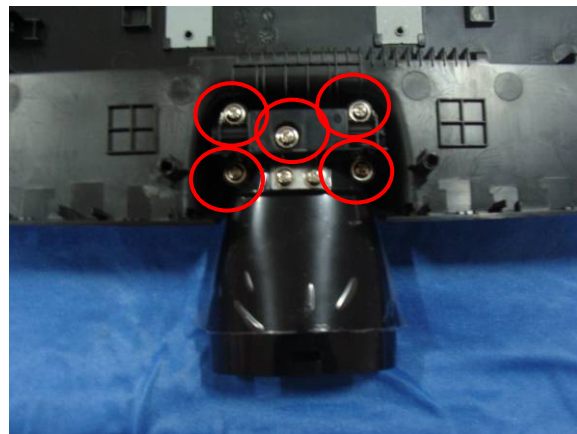
The panel.

#13



Rear cover and hinge ASS'Y.

#14



Disassemble the rear cover and hinge ASS'Y.

#15



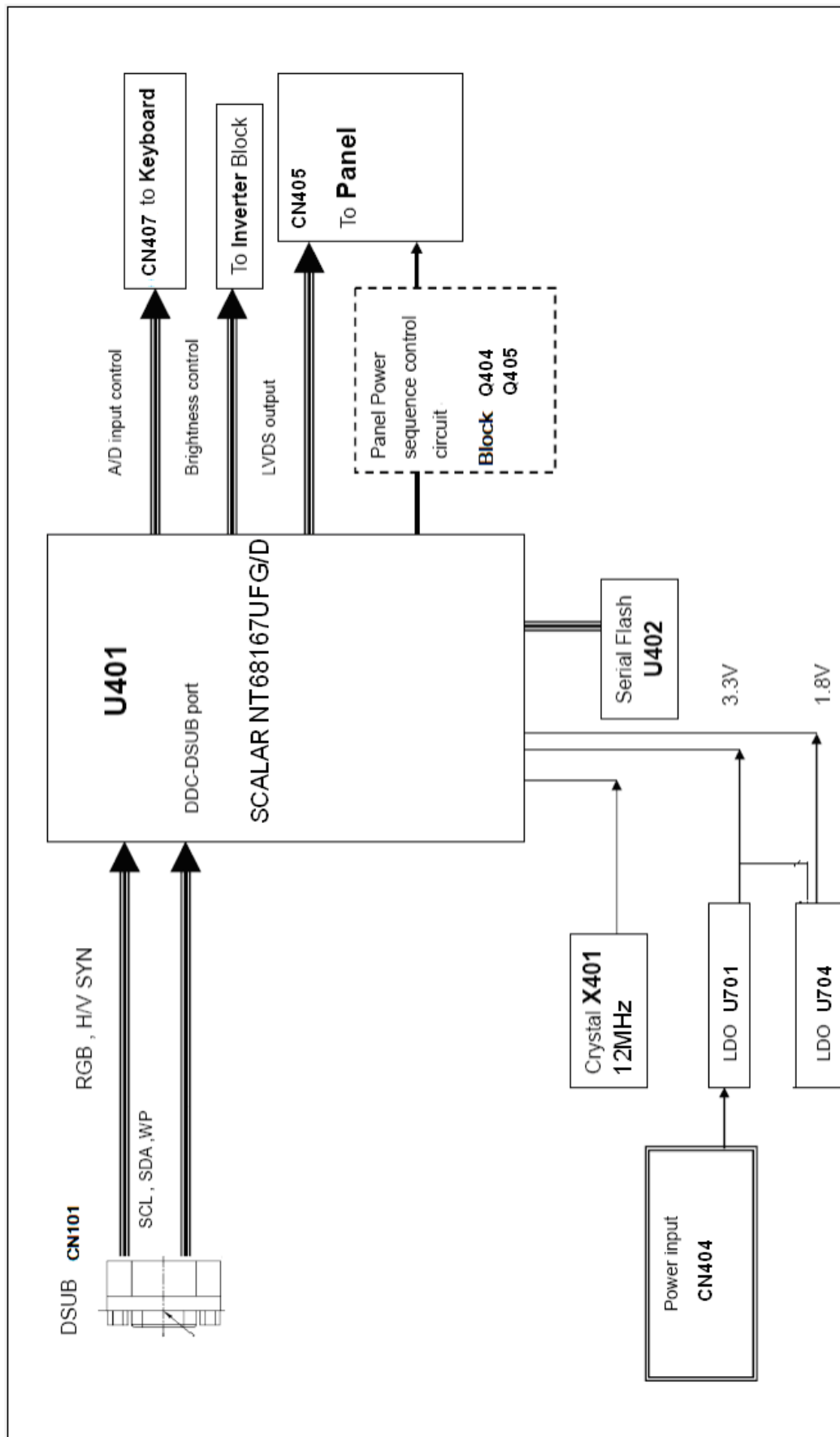
Disassemble the hinge and stand.

#16



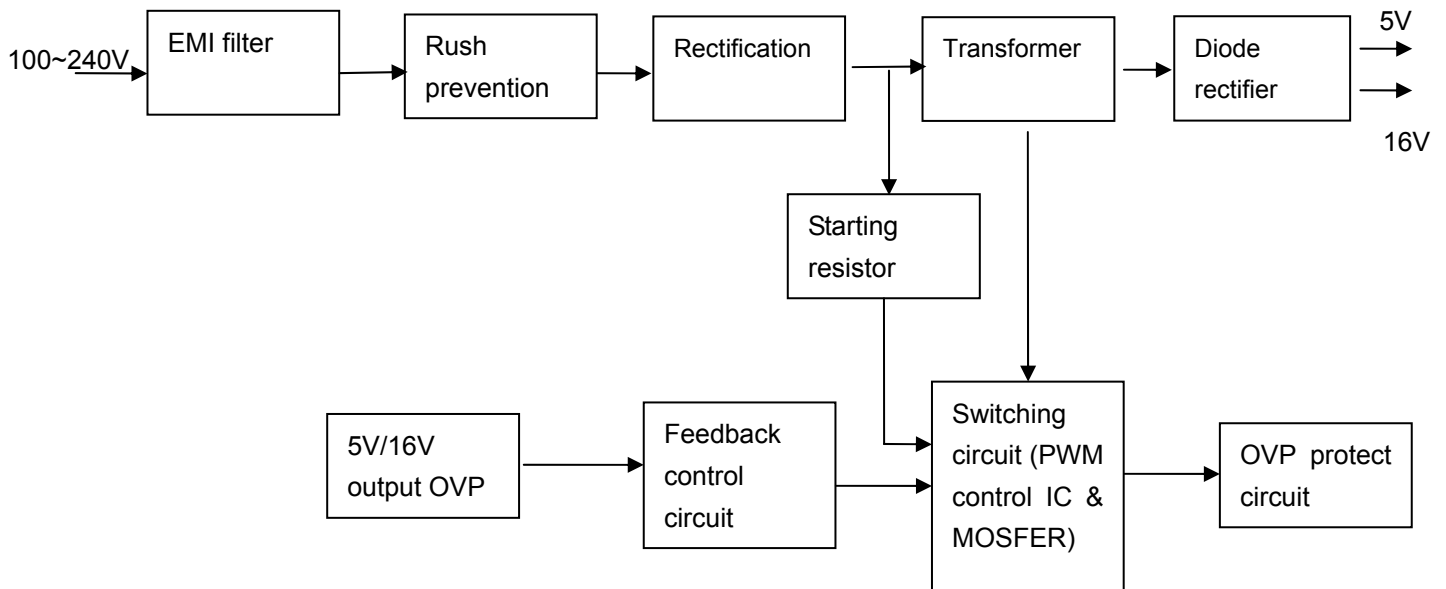
Hinge top, hinge and stand.

BLOCK DIAGRAM

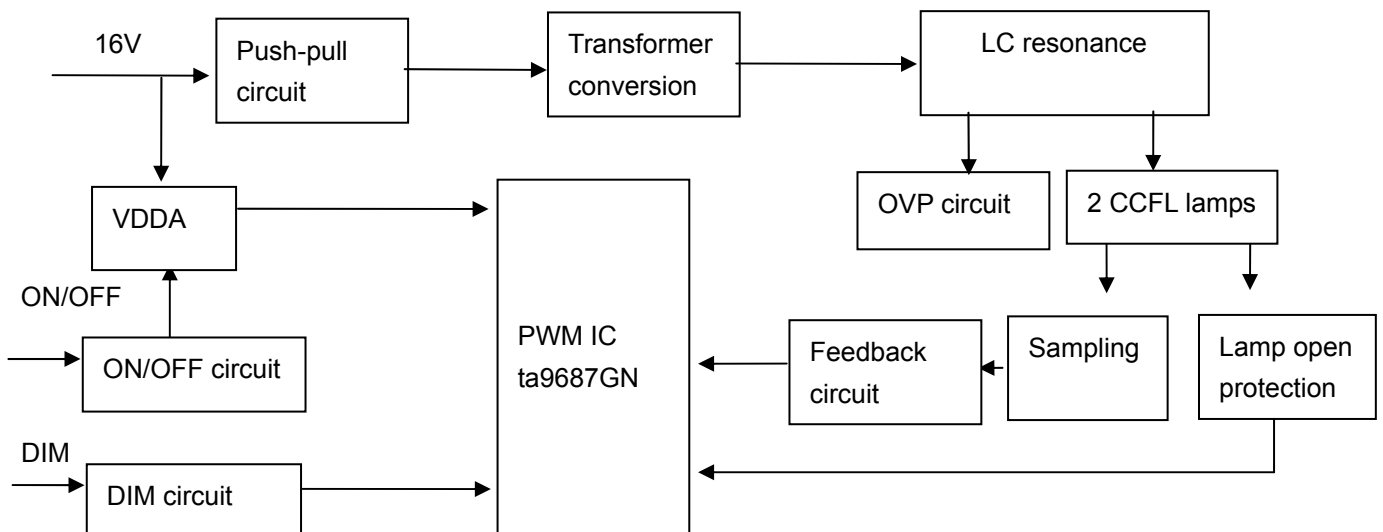


BLOCK DIAGRAM-POWER

Power



Inverter



DESCRIPTION OF BLOCK DIAGRAM

1. Video Controller Part.

This part amplifies the level of video signal for the digital conversion and converts from the analog video signal to the digital video signal using a pixel clock.

The pixel clock for each mode is generated by the PLL.

The range of the pixel clock is from 25MHz to 148.5MHz.

This part consists of the Scalar, ADC converter, TMDS receiver and LVDS transmitter.

The Scalar gets the video signal converted analog to digital, interpolates input to 1920 X 1080 resolution signal and outputs 8-bit R, G, B signal to transmitter.

2. Power Part.

This part consists of the one 3.3V, and one 1.8V regulators to convert power which is provided 5V in Power board.

16V is provided for inverter, 5V is provided for LCD panel.

Also, 5V is converted 3.3V and 1.8V by regulator. Converted power is provided for IC in the main board.

The inverter converts from DC 16V to AC 700Vrms and operates back-light lamps of module.

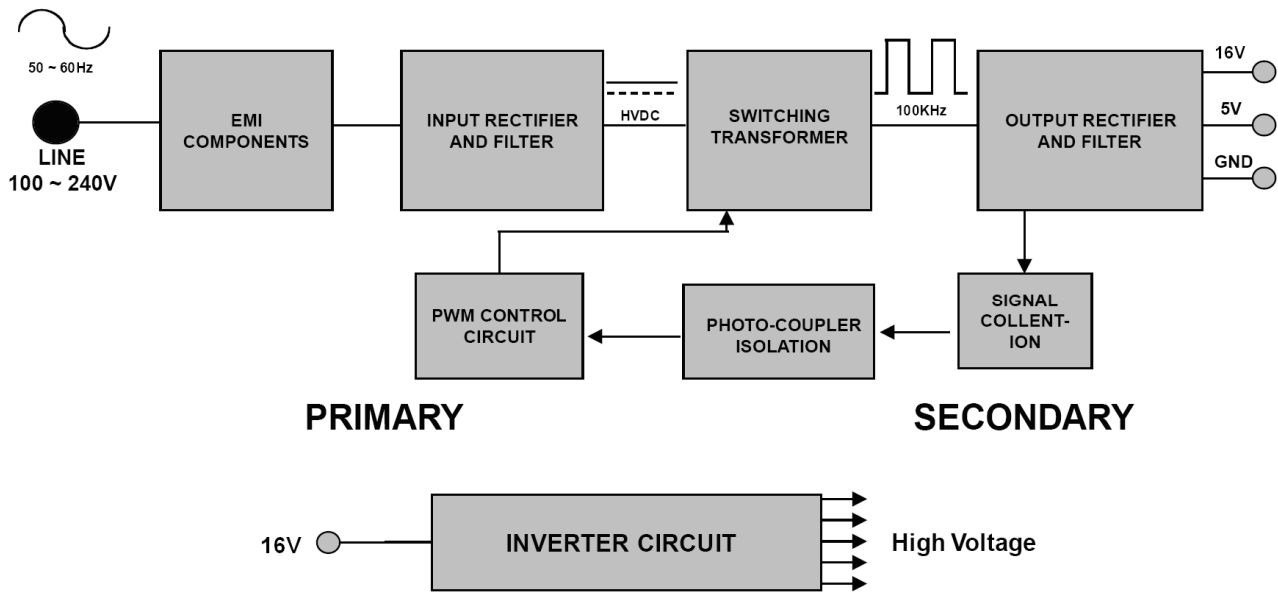
3. MICOM Part.

This part is including video controller part. And this part consists of Reset IC and the Micom.

The Micom distinguishes polarity and frequencies of the H/V sync are supplied from signal cable.

The controlled data of each mode is stored in scalar.

LIPS Board Block Diagram



Operation Description_LIPS

1. EMI components.

This part contains of EMI components to comply with global marketing EMI standards like FCC, VCCI CISPR, the circuit included a line-filter, across line capacitor and of course the primary protection fuse.

2. Input rectifier and filter.

This part function is for transfer the input AC voltage to a DC voltage through a bridge rectifier and a bulk capacitor.

3. Energy Transfer.

This part function is for transfer the primary energy to secondary through a power transformer.

4. Output rectifier and filter.

This part function is to make a pulse width modulation control and to provide the driver signal to power switch, to adjust the duty cycle during different AC input and output loading condition to achieve the dc output stabilized, and also the over power protection is also monitor by this part.

5. Photo-Coupler isolation.

This part function is to feed back the DC output changing status through a photo transistor to primary controller to achieve the stabilized DC output voltage.

6. Signal collection.

This part function is to collect the any change from the DC output and feed back to the primary through photo transistor.

ADJUSTMENT

Windows EDID V1.0 User Manual

Operating System: DOS, windows98, 2000, XP

1. Parallel port setting

Enter your bios, and do as followings.

- a) Integrated peripheral
- b) Super IO Device
- c) Parallel port mode

you should set the" parallel port mode" to SPP for using the DOS EDID tool surely.

2. EDID Write

- 1、Connect the signal line of monitor with DDC recorder.
- 2、Choose the DDC RECORD program, and it shows on the screen, the choose the correct source base on the monitor.
- 3、Click "LoadFile" ,then key in the **manufacturer name**、**model name**、**product code**, then choose the correct model name base on the monitor.(as Fig.2)
- 4、Scan serial No. to DDC recorder by Bar Reader, then read again in the Verify SN.
- 5、According to the message of DDC program, when the picture as fig.1 appears, it show DDC record has finished.

EDID Programmer (TPVDDC5.6)

Help History Read

LoadFile... 22GSM\W2243(试跑) Flush Analog DVI Analog and DVI

	00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F
01	00	FF	FF	FF	FF	FF	FF	00	1E	6D	FE	56	58	CC	04	00
02	38	0E	01	03	6A	30	1B	78	EA	AE	C5	A2	57	4A	9C	25
03	12	50	54	A5	4B	00	B3	00	81	80	71	4F	81	CF	81	4F
04	01	01	01	01	01	01	1A	36	80	A0	70	38	1F	40	30	20
05	25	00	DD	0D	11	00	00	1A	02	3A	80	18	71	38	2D	40
06	58	2C	45	00	DD	0D	11	00	00	1E	00	00	00	FD	00	38
07	4B	1E	53	0F	00	0A	20	20	20	20	20	20	20	00	00	FC
08	00	57	32	32	34	33	0A	20	20	20	20	20	20	20	00	48

	00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F
01	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
02	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
03	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
04	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
05	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
06	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
07	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
08	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00

Analog

Manufacturer: GSM Product Code: 56FE

Model Name: W2243

Monitor SN:

Input: Analog Checksum: 48

Digital

Manufacturer: @@@ Product Code: 0000

Model Name:

Monitor SN:

Input: Analog Checksum: 00

Time input

Year-Month-Day: - - Year: 2004 Week: 56 [ISO8601] Flash independence dependence

CRC Check

W A3D0 R Analog W R DVI

D-SUB: PASS!

Program

Read A [Analog]

Read Both [Analog+Digital]

Read D [Digital]

State

Input SN 12

Fig.1

Please check **Manufacturer Name**、**Vendor Assigned Code**、**Monitor Name**、**Serial Number**: ****[????????? *****] (it must be the same as Bar Code)、**Week of Manufacture**: **、**Year of Manufacture**: ****、**Check sum**: ** (It must be the same as the last byte of data table, as follows picture shows). Above of all must be right, then if it shows the green “PASS”, it means record succeeds ,the red “Fail” means record fails; then check the power supply and signal line, and ensure they are connected well ,then do DDC record again from the third step.

The image shows a software window titled "Select" with a close button (X) in the top right corner. Inside the window, there are two checked checkboxes: "Analog" and "Digital". Below these, there are two sections: "Analog" and "Digital". Each section contains three input fields: "Manufacturer" (with "GSM" entered), "Product Code" (with "56FE" for Analog and "56FF" for Digital entered), and "Model Name" (with "W2243" entered). To the right of these input fields are two buttons: "Next" and "Cancel".

Fig.2

SERVICE MODE

- 1) Turn off the power switch at the front side of the display.
- 2) Wait for about 5 seconds and press MENU, POWER switch with 1 second interval.
- 3) The SVC OSD menu contains additional menus that the User OSD menu as described below.

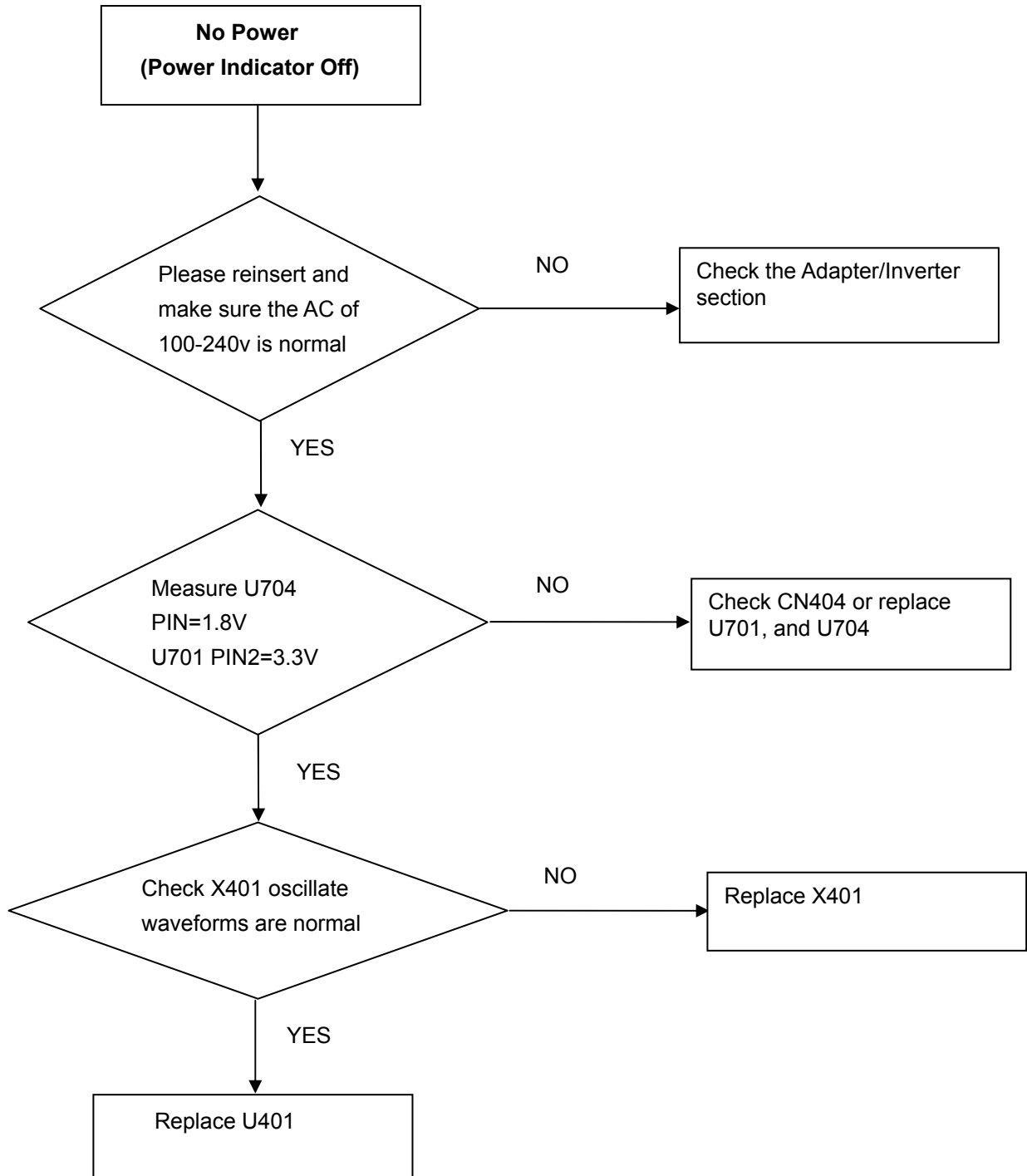
- a) CLEAR ETI: To initialize using time.
- b) Auto Color: W/B balance and automatically sets the gain and offset value.
- c) AGING: Select Aging mode (on/off).
- d) PANEL: used panel type
- e) NVRAM INIT: NO
- f) R/G/B-9300K: Allows you to set the R/G/B-9300K value manually.
- g) R/G/B-6500K: Allows you to set the R/G/B-6500K value manually.
- h) R/G/B-Offset: Allows you to set the R/G/B-Offset value manually. (Analog Only)
- i) R/G/B-Gain: Allows you to set the R/G/B-Gain value manually. (Analog Only)



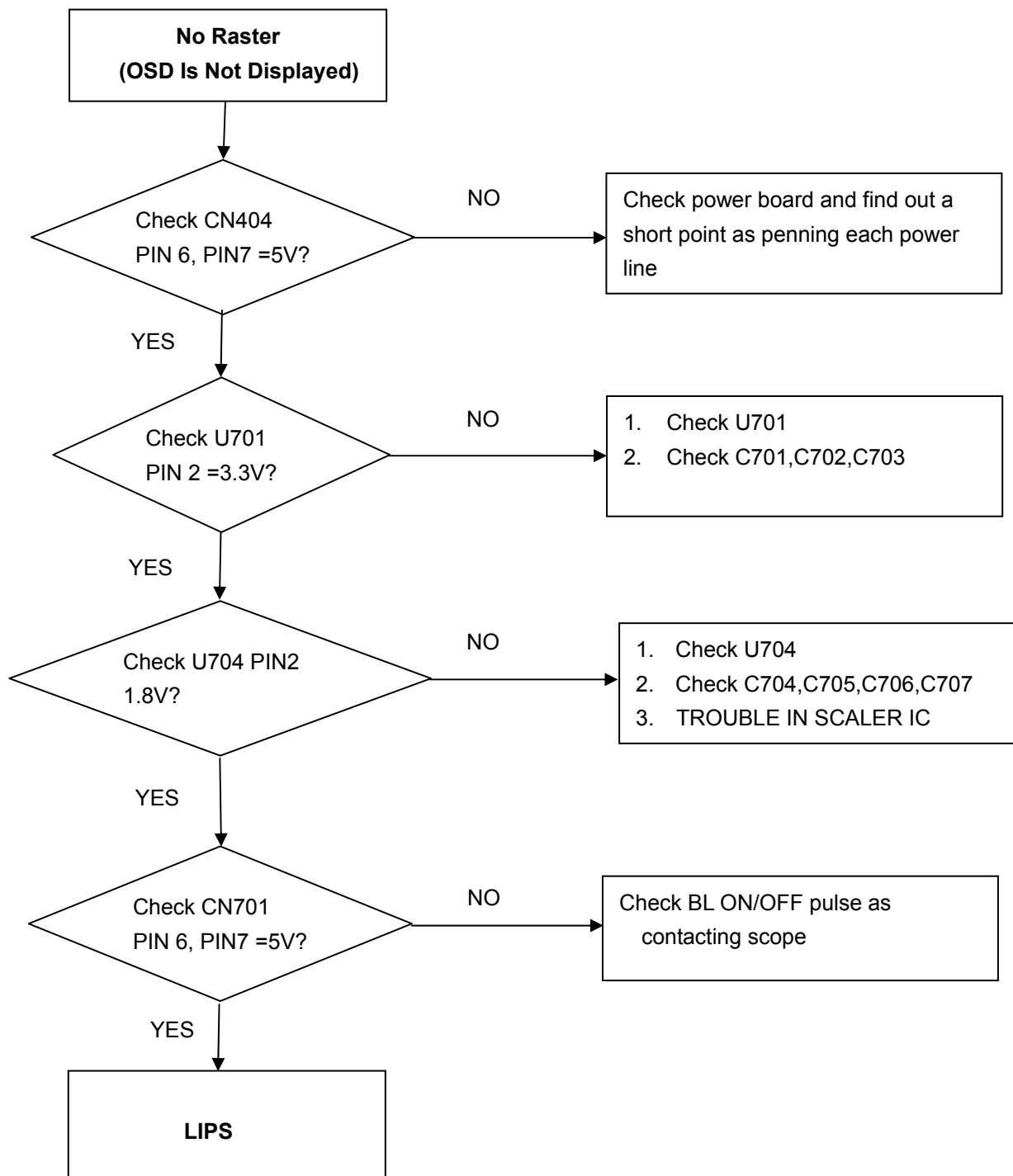
Figure 1 Cable Connection for Micom uploading

TROUBLESHOOTING GUIDE

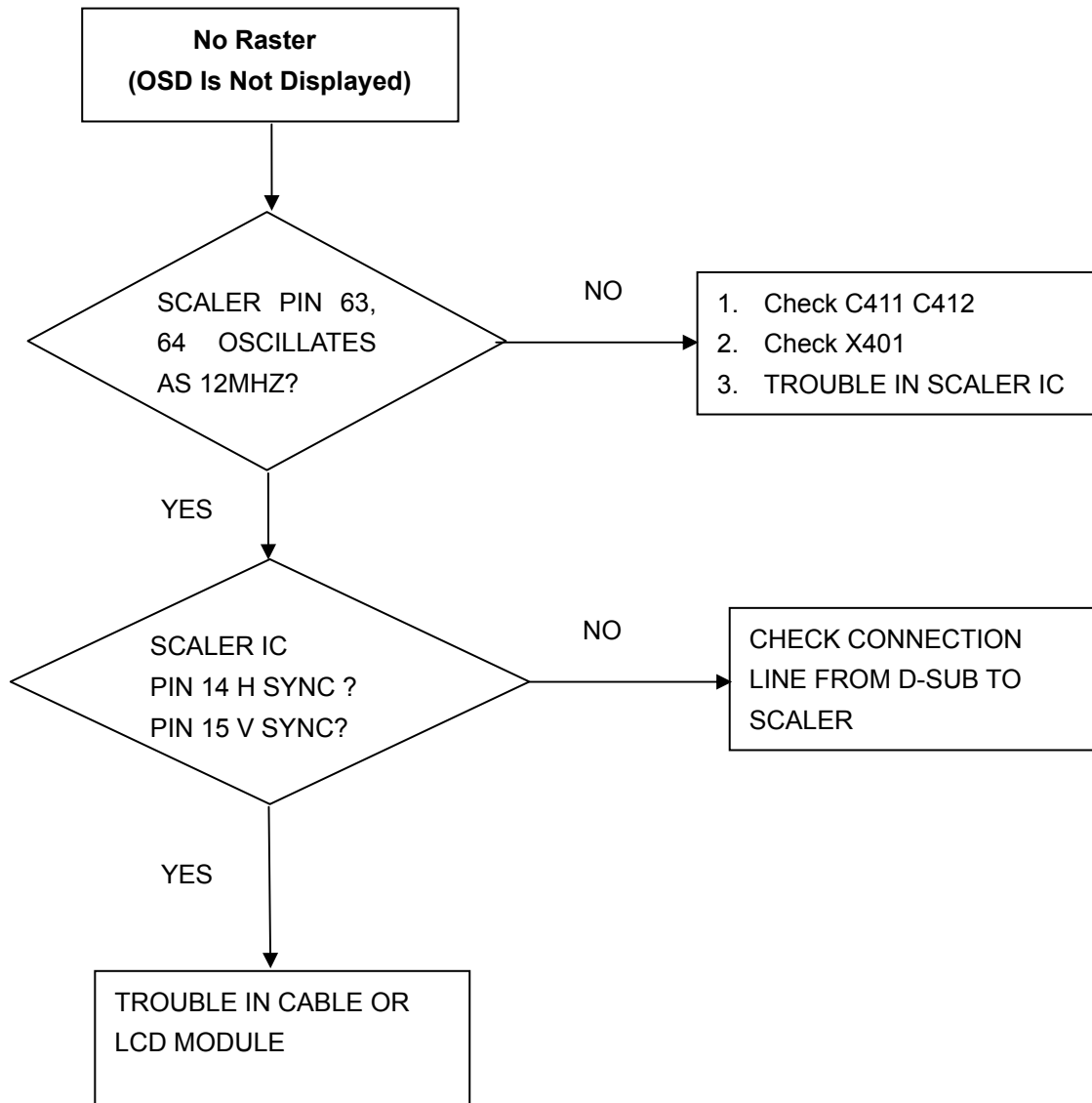
1. NO POWER



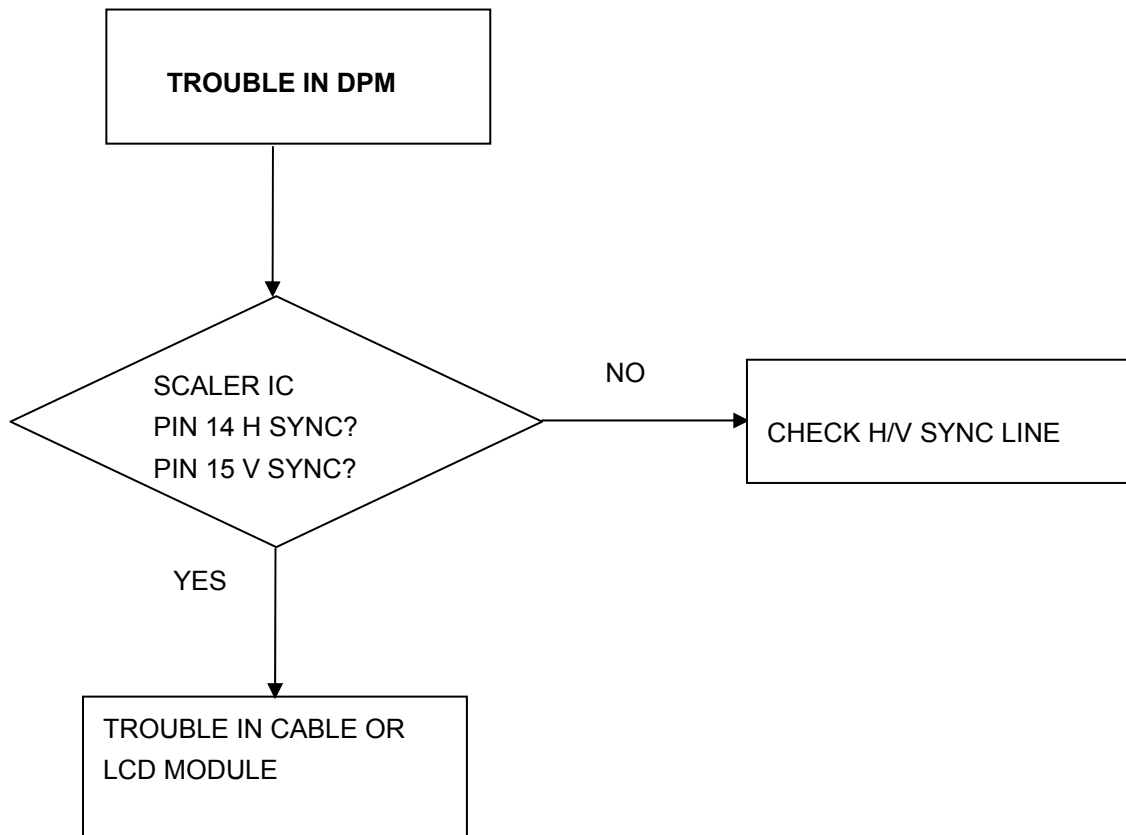
2. NO RASTER (OSD IS NOT DISPLAY)-LIPS



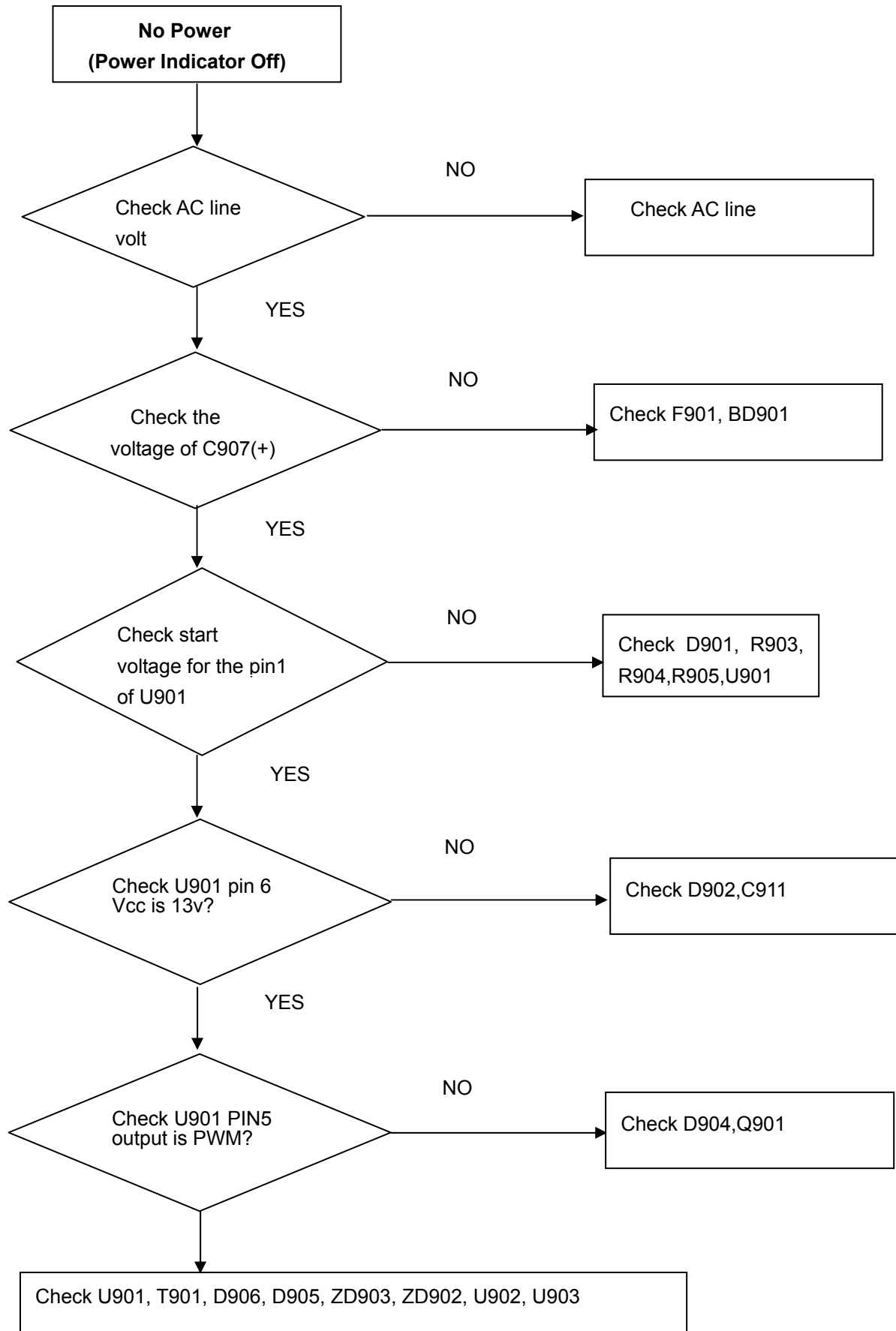
3. NO RASTER (OSD IS NOT DISPLAY)-MSTAR



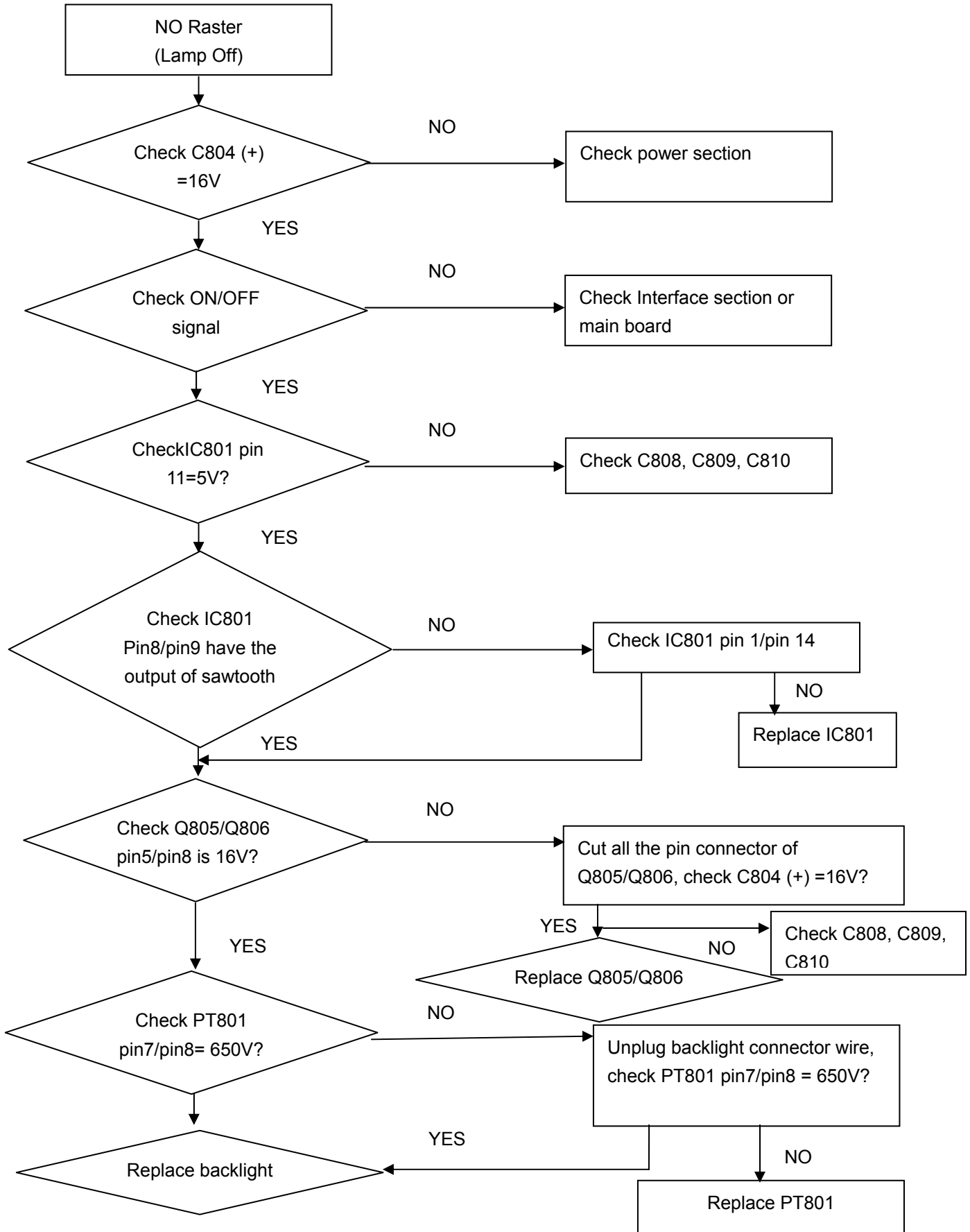
4. TROUBLE IN DPM



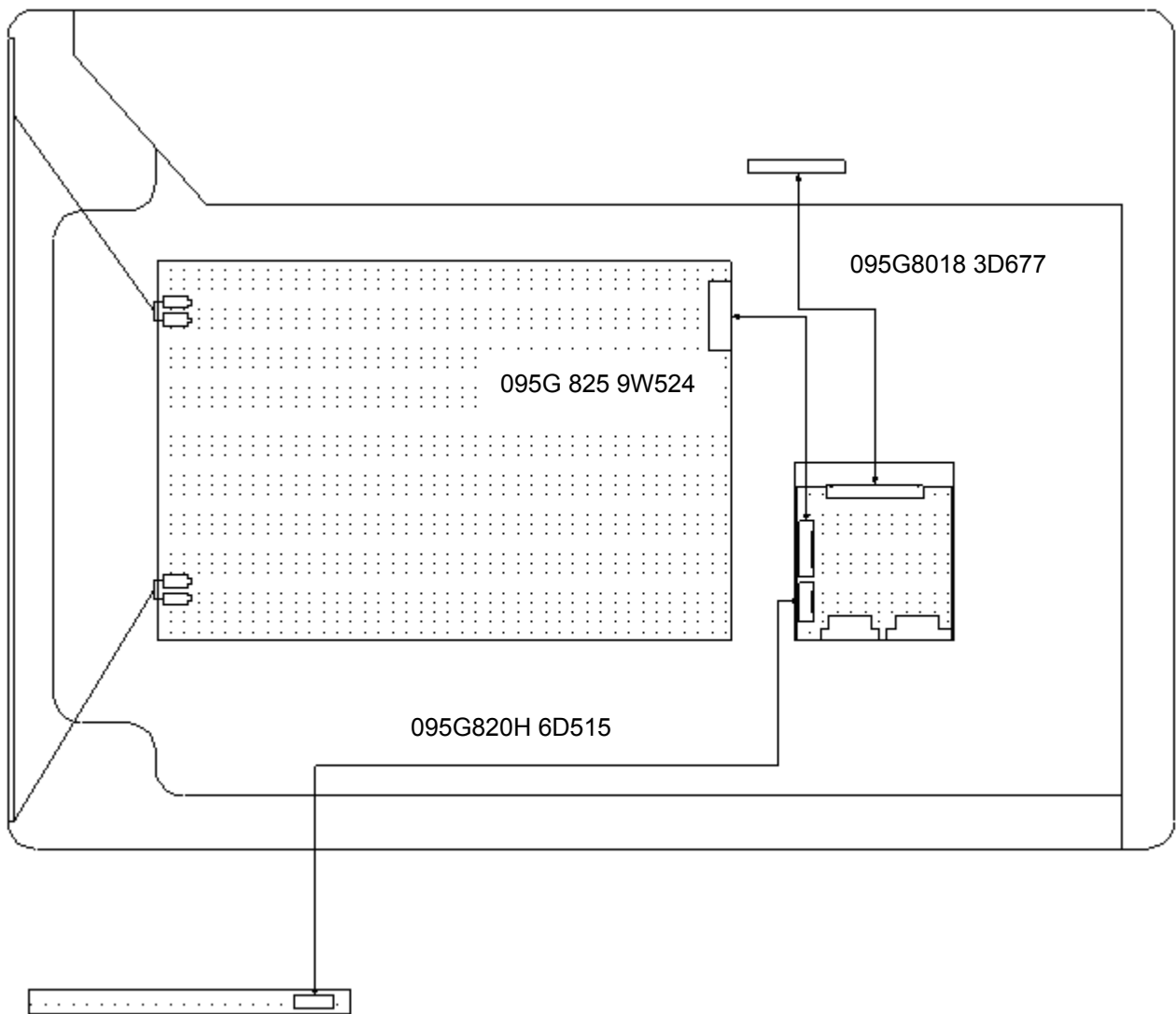
5. POWER



6. RASTER




WIRING DIAGRAM





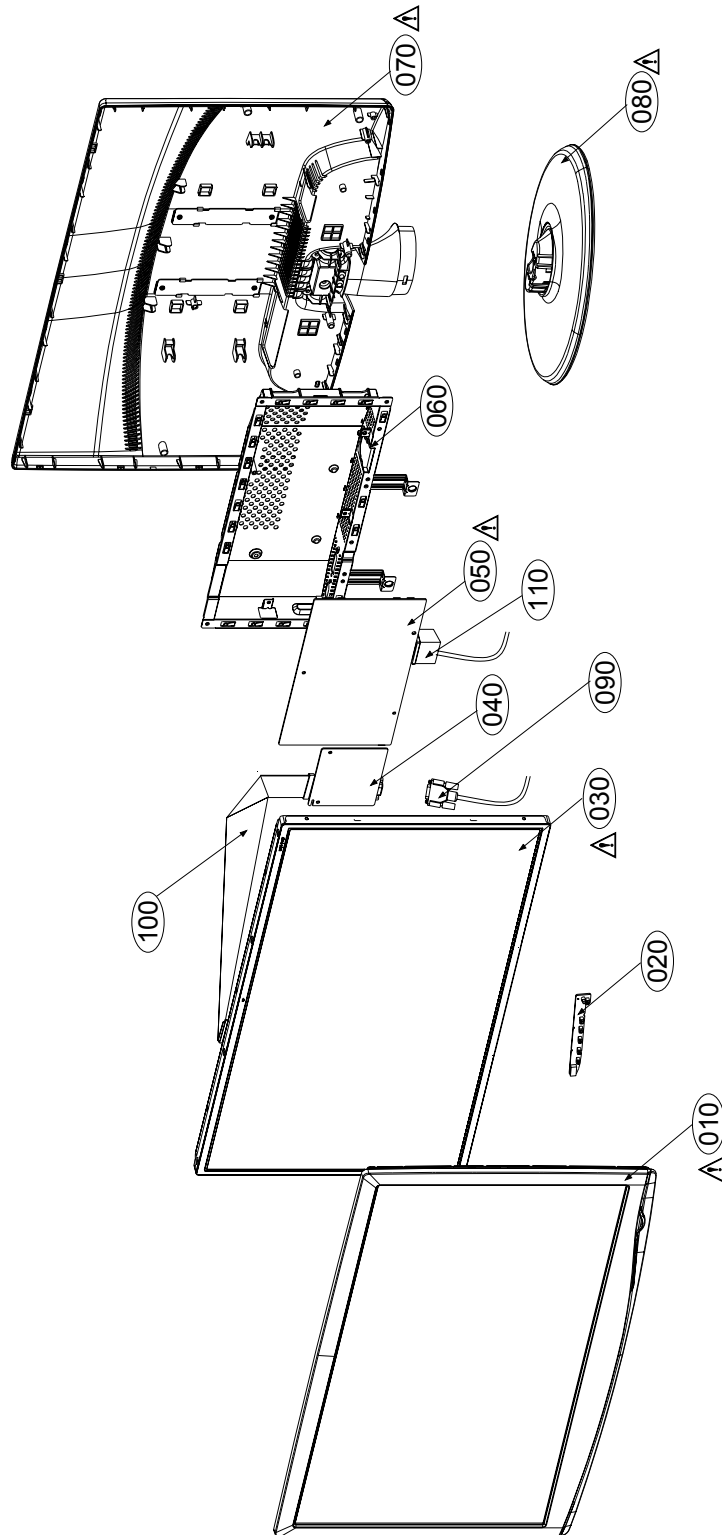
EXPLODED VIEW

IMPORTANT SAFETY NOTICE

Many electrical and mechanical parts in this chassis have special safety-related characteristics. These parts are identified by  in the EXPLODED VIEW.

It is essential that these special safety parts should be replaced with the same components as recommended in this manual to prevent X-RADIATION, Shock, Fire, or other Hazards.

Do not modify the original design without permission of manufacturer.

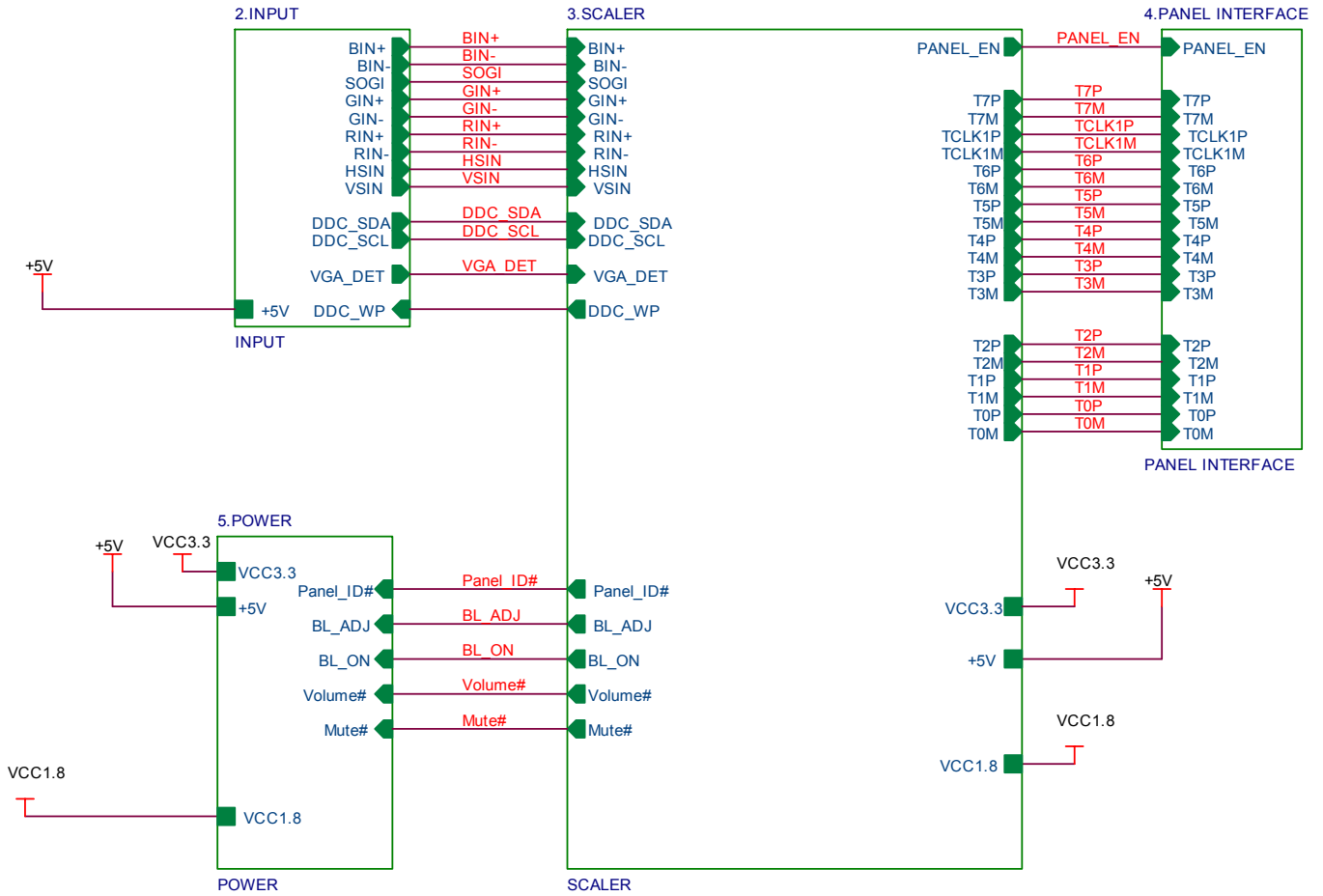


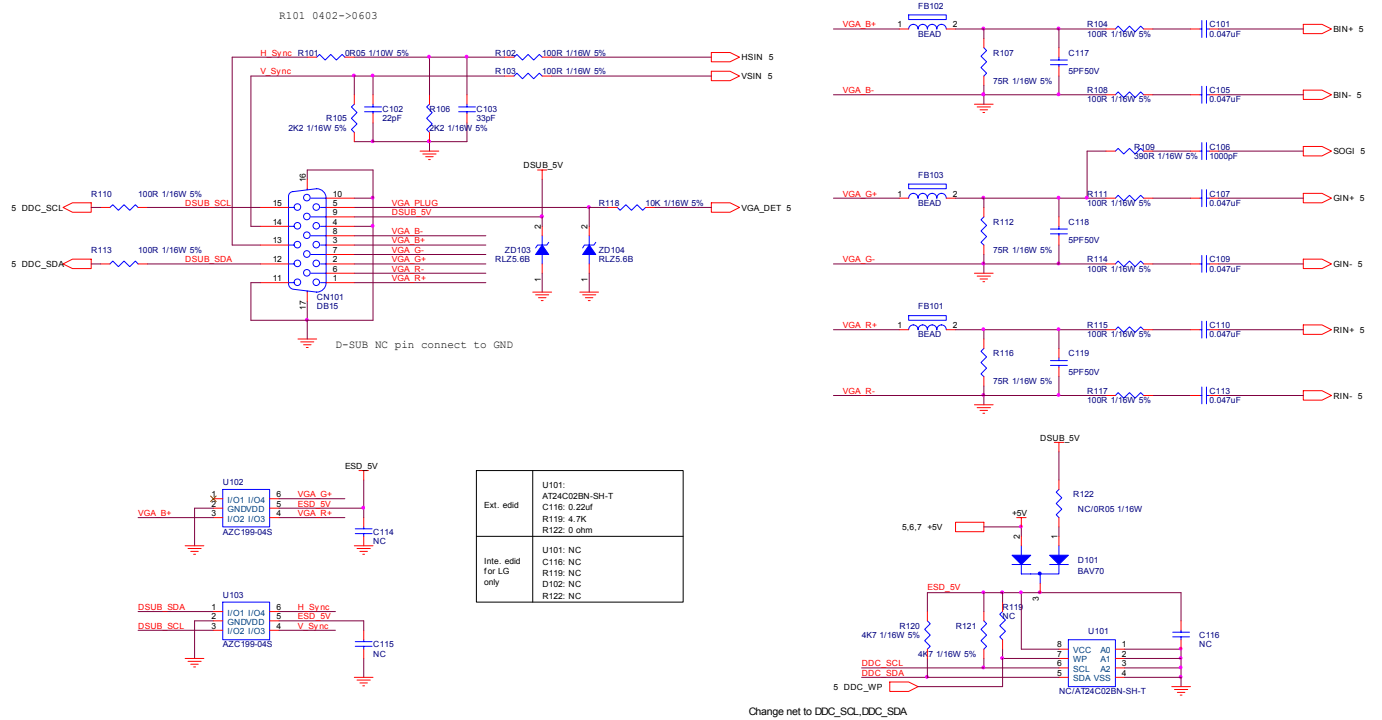
EXPLODED VIEW PARTS LIST

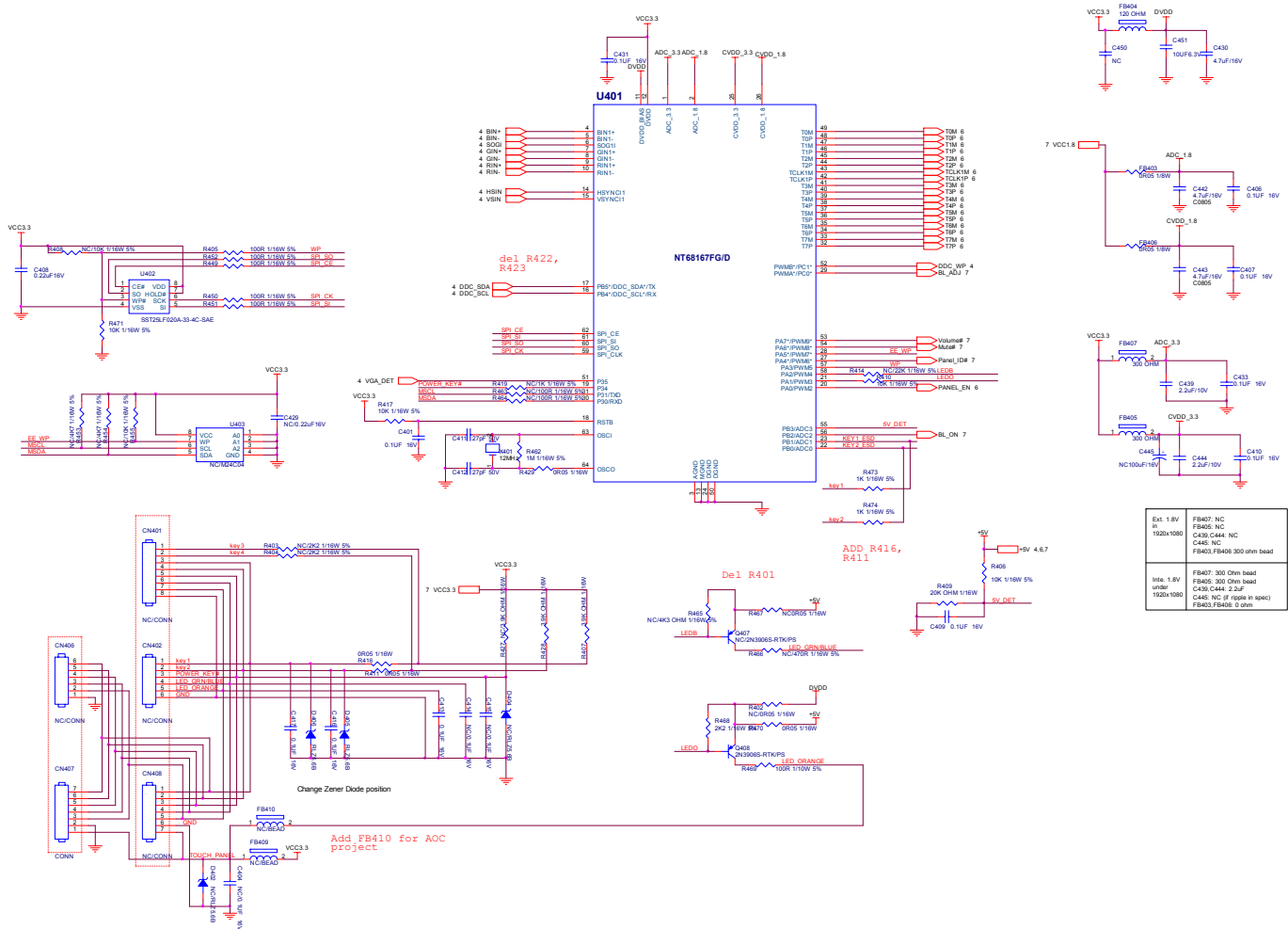
Ref. No.	TPV part no.	LGE part no.	Description
010	705GQ9CS030	ACQ74060006	BEZEL ASSY FOR AUO
	705GQ9CS029	ACQ74060005	BEZEL ASSY FOR LGD
020	KEPC8QG2	EBU60704501	KEY BOARD
030	750GLU215H1013N000	COV30109701	PANEL M215HW01 V00 XM AUO
	750GLG215W1A13M0LG	COV30109801	PANEL LM215WF1-TLA1 GZ LGD
040	756GQ8CB KL012	EBU60714901	MAIN BOARD- CBPCRNLGQ1 FOR AUO
	756GQ9CB KL001	EBU60715001	MAIN BOARD- CBPCRNLGQ1 FOR LGD
050	PWPC8C41LYB1	EBU60714801	POWER BOARD
060	Q15G0415101	MDQ61891305	MAIN FRAME
070	705GQ934046	ACQ74060105	REAR COVER/HINGE/STAND ASS'Y
080	705GQ9CS028	ACQ74060202	BASE ASSY
090	089G 728HAA 2G	COV30013801	SIGNAL CABLE
100	095G8018 3D677	COV30109901	LVDS CABLE 30P-30P 160MM
110	089G421A18N IS	EAD37992101	POWER CORD
	Q44GC094689 1A	MAY61869704	22 LCD CARTON
	Q44GC094101	MFZ61984003	EPS (Bottom)
	Q44GC094201		EPS (Top)

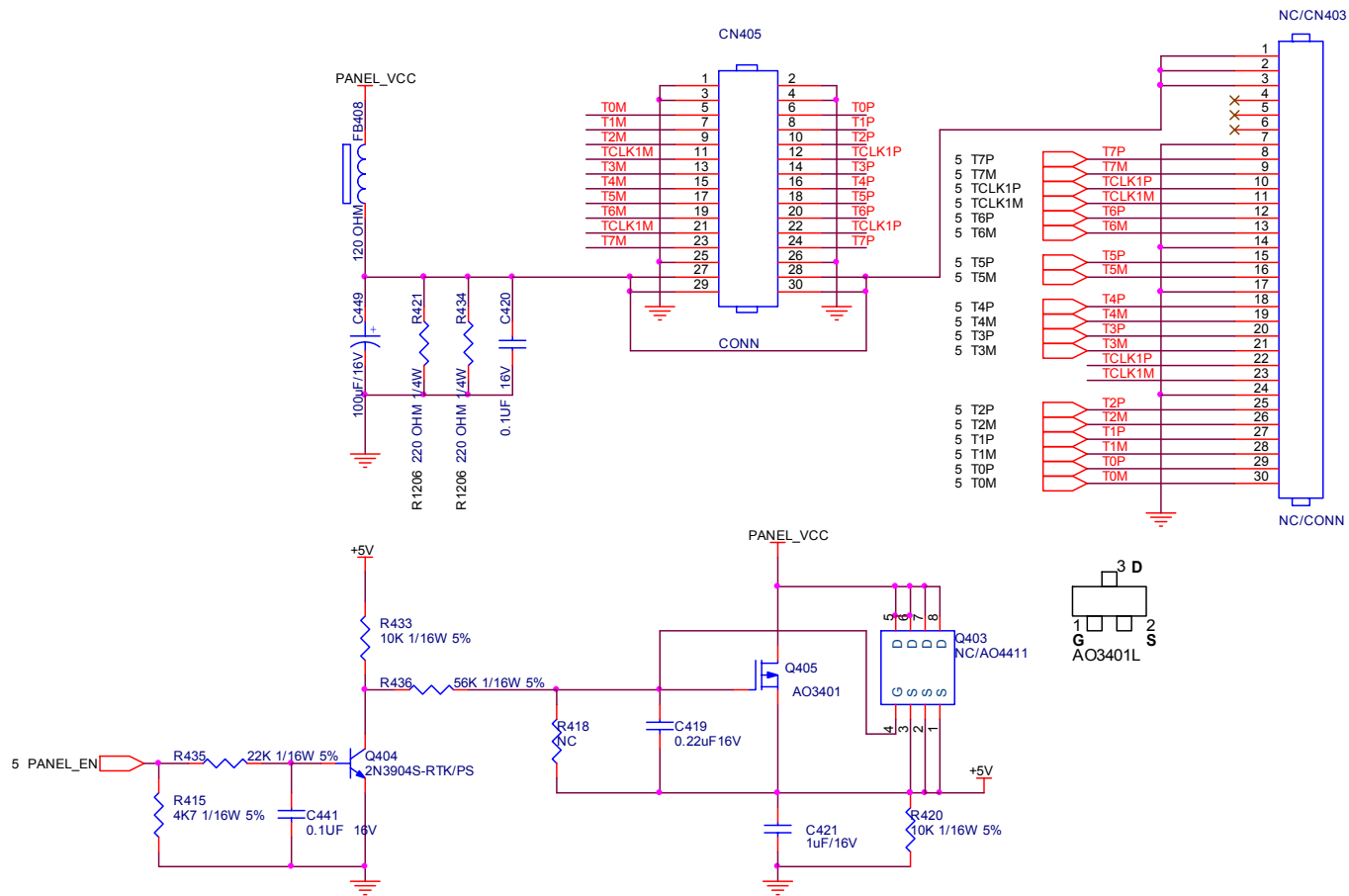
SCHEMATIC DIAGRAM

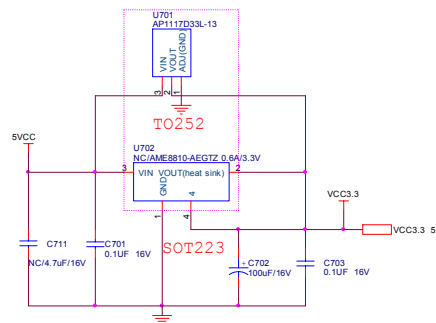
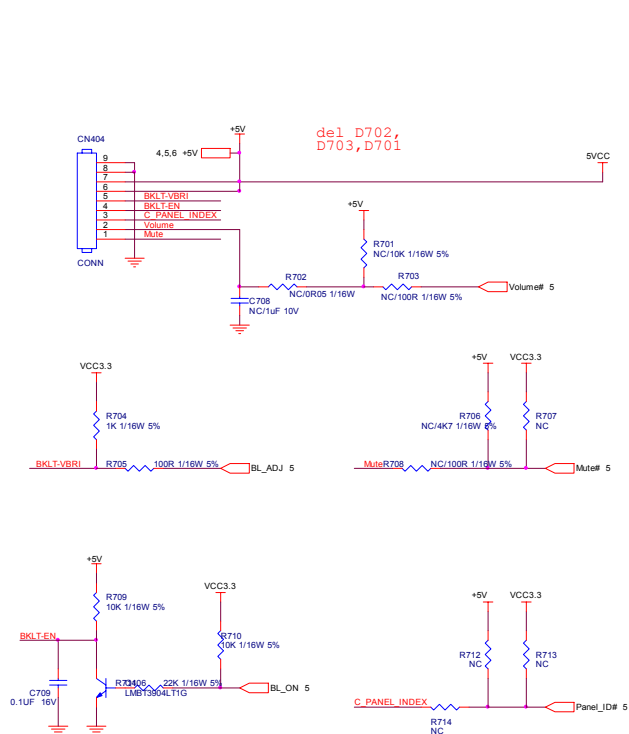
1. SCALER



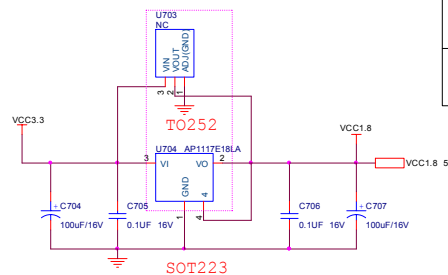




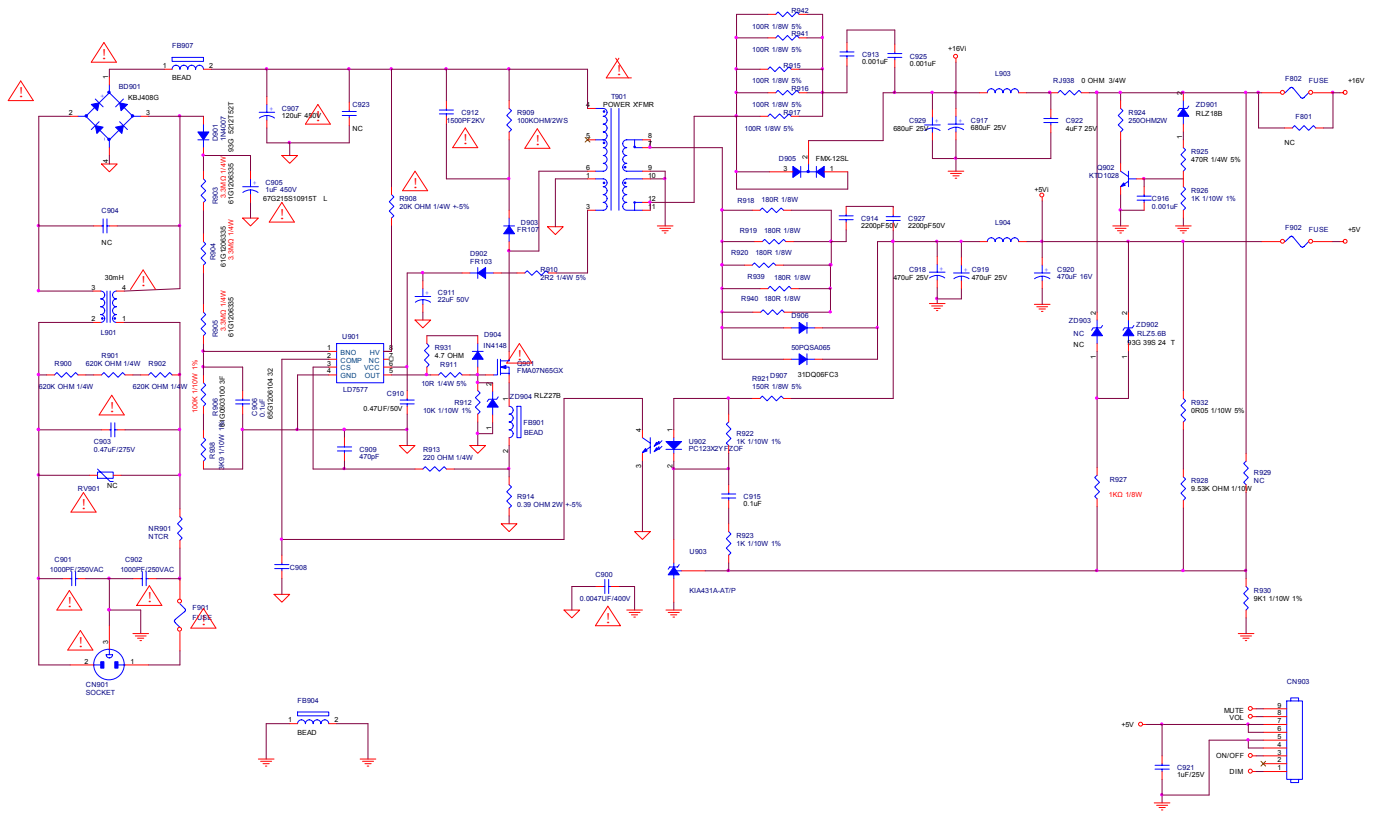




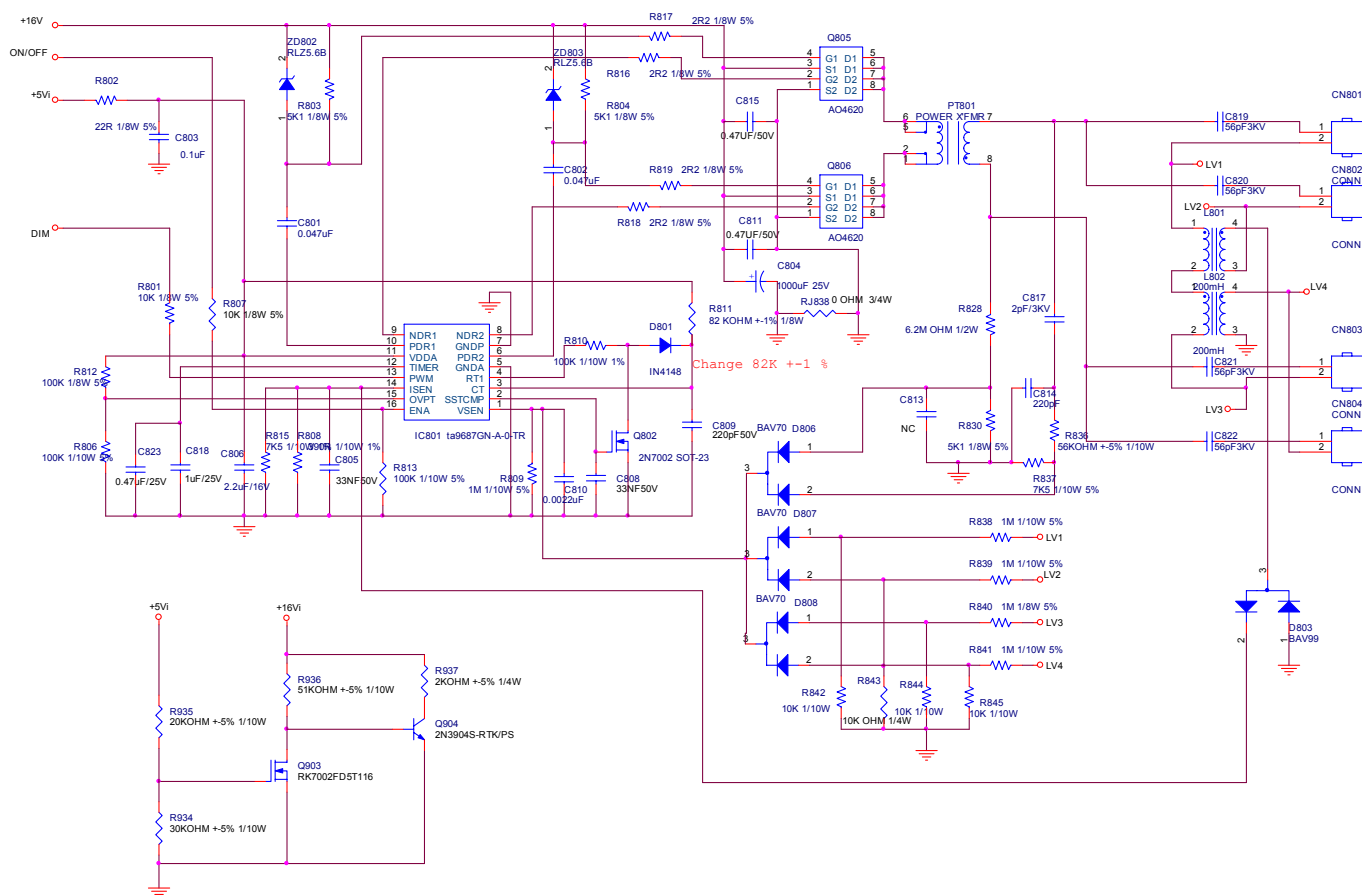
Ext. 1.8V	U703/U704: AP1117E18LA(SOT223) C705: 0.1uF C704: 100uF/16V
Inte. 1.8V	U703/U704: NC C705: NC C704: 100uF/16V



2. POWER



3. INVERTER





P/NO:

Mar.2009
Printed in China